

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	193	(228/49.5).CCLS.	USPAT	OR	OFF	2005/08/17 15:27
L2	166	(228/47.1).CCLS.	USPAT	OR	OFF	2005/08/17 15:27
L4	162	2 not 1	USPAT	OR	OFF	2005/08/17 15:31
L5	104	(1 or 2) and (vacuum or suck\$4 or suction\$4 or negative adj pressure)	USPAT	OR	ON	2005/08/17 15:32
L6	10	5 and (vacuum or suck\$4 or suction\$4 or negative adj pressure) near (board or substrate or pcb or pwb)	USPAT	OR	ON	2005/08/17 15:32

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	23466	("pick and place" or "pick-and-place" or pick near place or (vacuum or suck\$4 or suction or actuat\$4) near (tool or head or collet or nozzle or means or device or apparatus)) and (photograph\$4 or camera or imag\$4) and (position\$4 or placing or place\$5 or align\$5 or register\$4 or registration) and (board or pcb or pwb or component or semiconductor or "ic" or circuit or chip or die or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 14:52
L2	120	1 and (("pick and place" or "pick-and-place" or pick near place or (vacuum or suck\$4 or suction) near (tool or head or collet or nozzle)) or position\$4 or placing or place\$5 or align\$5 or register\$4 or registration) near (solder adj (ball or sphere or preform))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 14:55
L3	7082	((228/20.1,102-105,180.21,180.22,245,246) or (228/4.1,6.2,8-10,12,47.1,49.1,49.5)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/17 14:56
L4	166	3 and ("pick and place" or "pick-and-place" or pick near place or (vacuum or suck\$4 or suction or actuat\$4) near (tool or head or collet or nozzle or means or device or apparatus)) and (photograph\$4 or camera or imag\$4) and (position\$4 or placing or place\$5 or align\$5 or register\$4 or registration) and (board or pcb or pwb or component or semiconductor or "ic" or circuit or chip or die or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/17 14:56

L5	178	3 and ("pick and place" or "pick-and-place" or pick near place or (vacuum or suck\$4 or suction or actuat\$4) near (tool or head or collet or nozzle or means or device or apparatus)) and (photograph\$4 or camera or imag\$4) and (position\$4 or placing or place\$5 or align\$5 or register\$4 or registration) and (board or pcb or pwb or component or semiconductor or "ic" or circuit or chip or die or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 14:56
L6	30	5 and (("pick and place" or "pick-and-place" or pick near place or (vacuum or suck\$4 or suction) near (tool or head or collet or nozzle)) or position\$4 or placing or place\$5 or align\$5 or register\$4 or registration) near (solder adj (ball or sphere or preform))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 14:57